

Claims

What is claimed is:

5

Sub Do

1. A semiconductor cassette reducer, comprising:

a first substantially U-shaped plate;

a second substantially U-shaped plate;

10

a plurality of wafer supports connecting the first substantially U-shaped plate to the second substantially U-shaped plate; and more than two retention springs attached to the first substantially U-shaped plate.

15

2. The semiconductor cassette reducer of claim 1, wherein the first substantially U-shaped plate has a pair of interior arm cutouts.

20

3. The semiconductor cassette reducer of claim 1, wherein the first substantially U-shaped plate has a base cutout.

25

Sub al 7

4. The semiconductor cassette reducer of claim 1, wherein a base to tip distance is less than an interior depth of a front opening unified pod.

Sub
SD 21
cont'd

5. The semiconductor cassette reducer of claim 1, wherein the plurality of wafer supports includes a pair of side panels connected to a pair of arms of the first substantially U-shaped plates.

5 6. The semiconductor cassette reducer of claim 5, wherein the pair of side panels have a plurality of lips.

10 7. The semiconductor cassette reducer of claim 1, wherein the first substantially U-shaped plate has an exterior partial S-shaped cutout.

8. The semiconductor cassette reducer of claim 1, wherein the plurality of wafer supports includes a pair of columns.

15 9. The semiconductor cassette reducer of claim 9, wherein the pair of columns have at least two positions.

20 10. A semiconductor cassette reducer, comprising:

a first substantially U-shaped plate having a first pair of arms each having a first arm ⁵³ cutout;

a second substantially U-shaped plate having a second pair of arms each having a second arm ⁵³ cutout;

25 a plurality of wafer supports connecting the first substantially U-shaped plate to the second substantially U-shaped plate.

sub B2
cont

11. The semiconductor cassette reducer of claim 10, further including a plurality of retention springs attached to the first substantially U-shaped plate.

5

12. The semiconductor cassette reducer of claim 11, wherein one of the plurality of retention ³⁸ springs is designed to mate with a lip of a front opening unified pod.

10

13. The semiconductor cassette reducer of claim 10, wherein the plurality of wafer supports include a wafer support panel attached to one of the first pair of arms.

15

14. A semiconductor cassette reducer comprising:

a first substantially U-shaped plate;

a second substantially U-shaped plate;

20

a first wafer support panel attached to a first arm of the first substantially U-shaped plate and to a first arm of the second substantially U-shaped plate; and

a second wafer support panel attached to a second arm of the first substantially U-shaped plate and to a second arm of the second substantially U-shaped plate.

25

15. The semiconductor cassette reducer of claim 14, further including a pair of column wafer supports attached to a base of the first substantially U-shaped plate and to a base of the second substantially U-shaped plate.

5

16. The semiconductor cassette reducer of claim 14, wherein the first substantially U-shaped plate has a plurality of flexible disks.

10

17. The semiconductor cassette reducer of claim 14, wherein the first substantially U-shaped plate has a pair of arms each having an interior cutout.

15

18. The semiconductor cassette reducer of claim 14, wherein a base to tip distance is less than a diameter of wafer designed for a front opening unified pod.